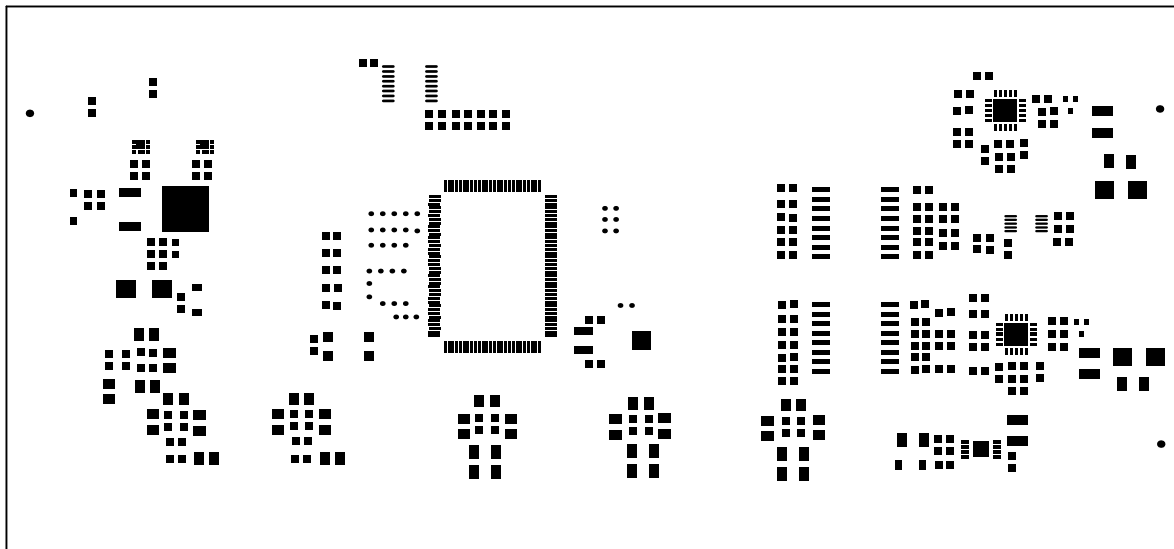
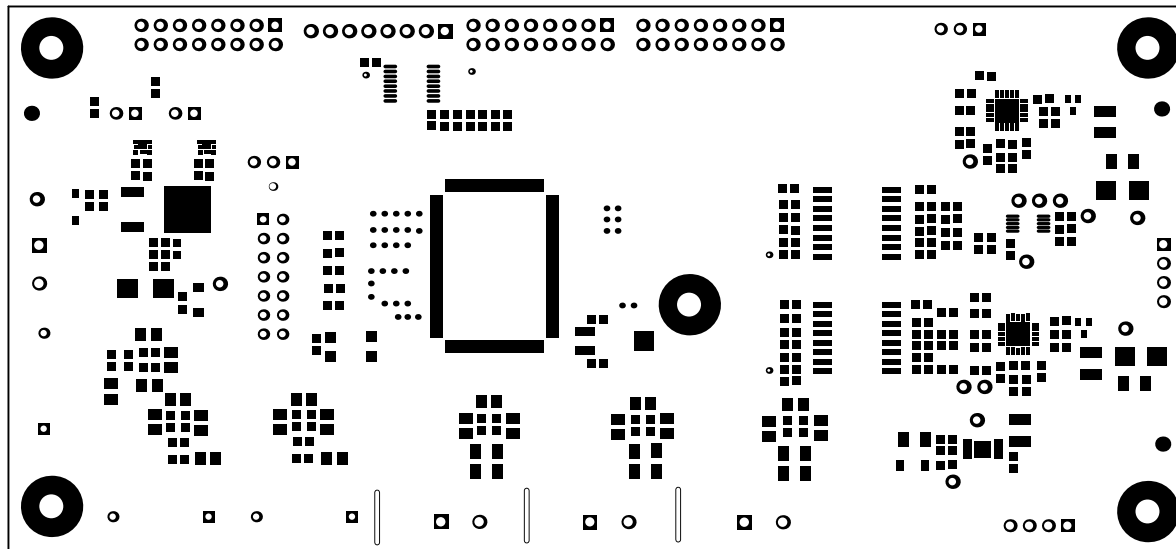


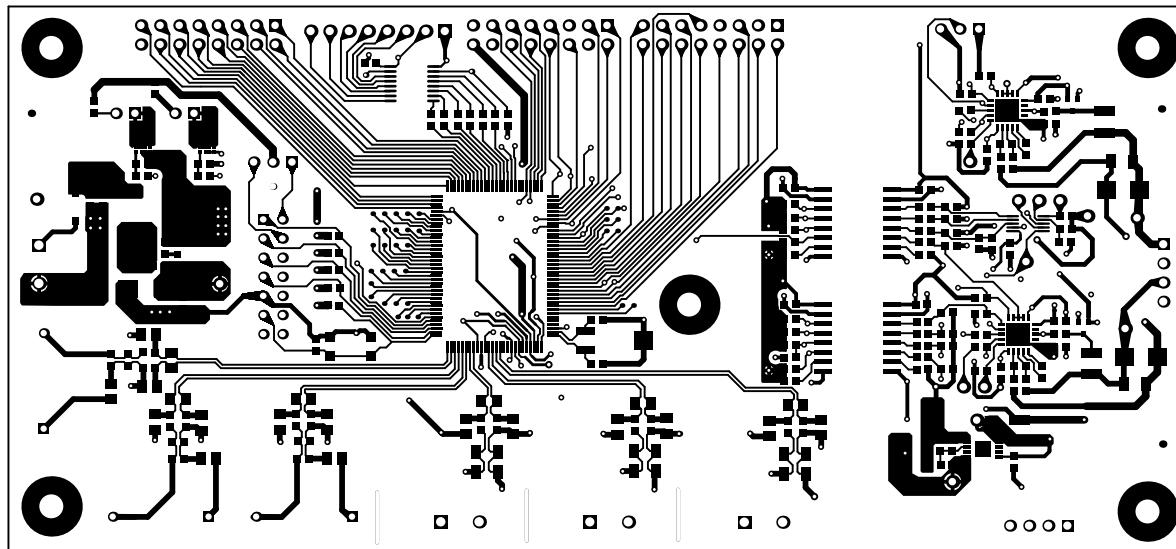
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00454	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 9/29/2015 2:48:52 PM	TEXAS INSTRUMENTS	



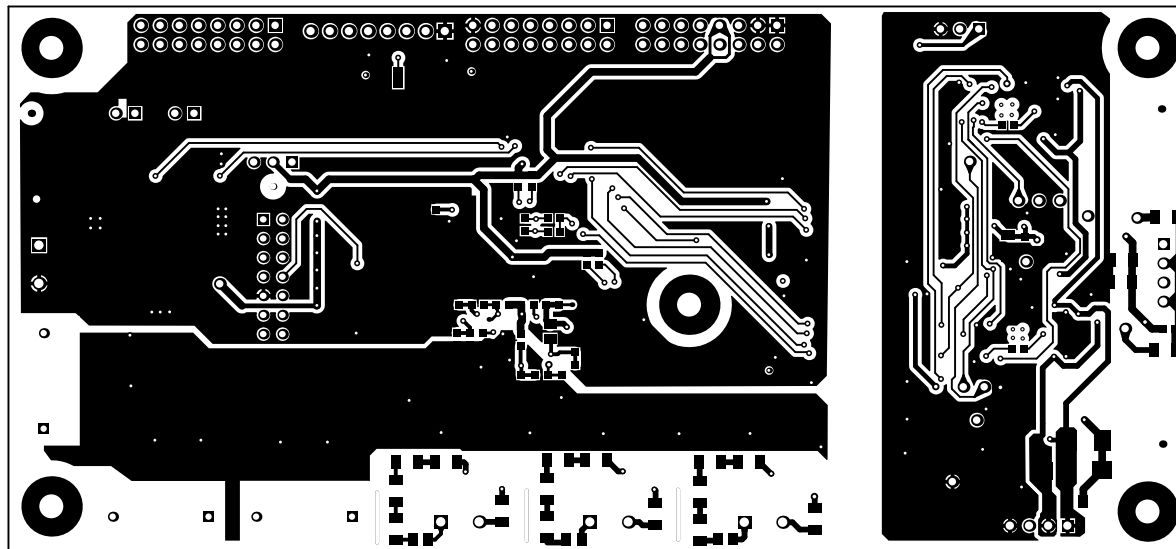
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00454	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Paste			
PLOT NAME = Top paste	GENERATED : 9/29/2015 2:48:52 PM	TEXAS INSTRUMENTS	



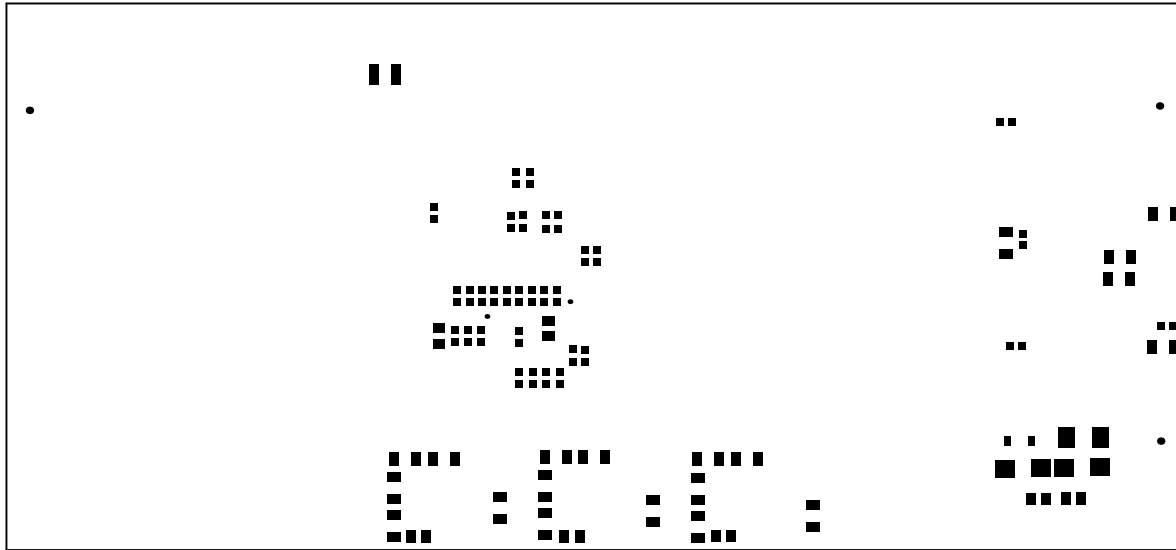
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00454	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 9/29/2015 2:48:52 PM	TEXAS INSTRUMENTS	



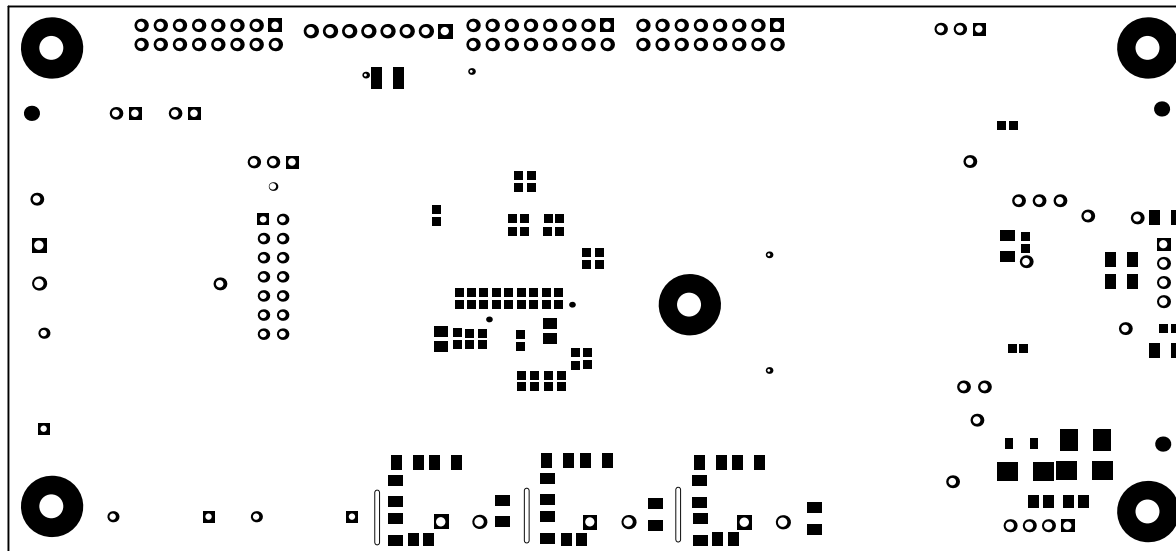
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00454	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 9/29/2015 2:48:53 PM	TEXAS INSTRUMENTS	



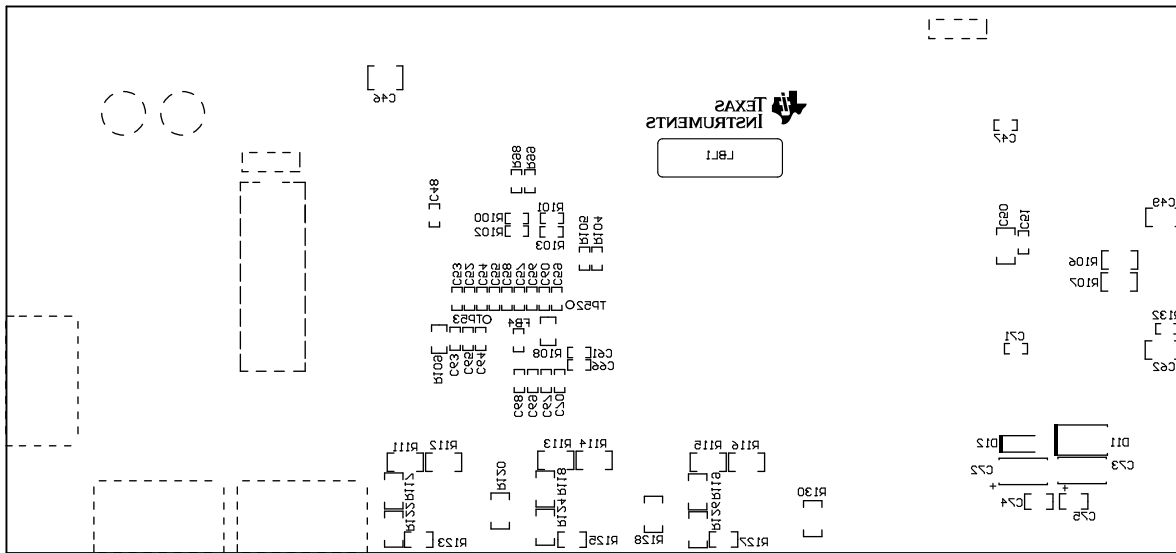
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00454	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 9/29/2015 2:48:53 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00454	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Paste			
PLOT NAME = Bottom Paste	GENERATED : 9/29/2015 2:48:53 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00454	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 9/29/2015 2:48:53 PM	TEXAS INSTRUMENTS	



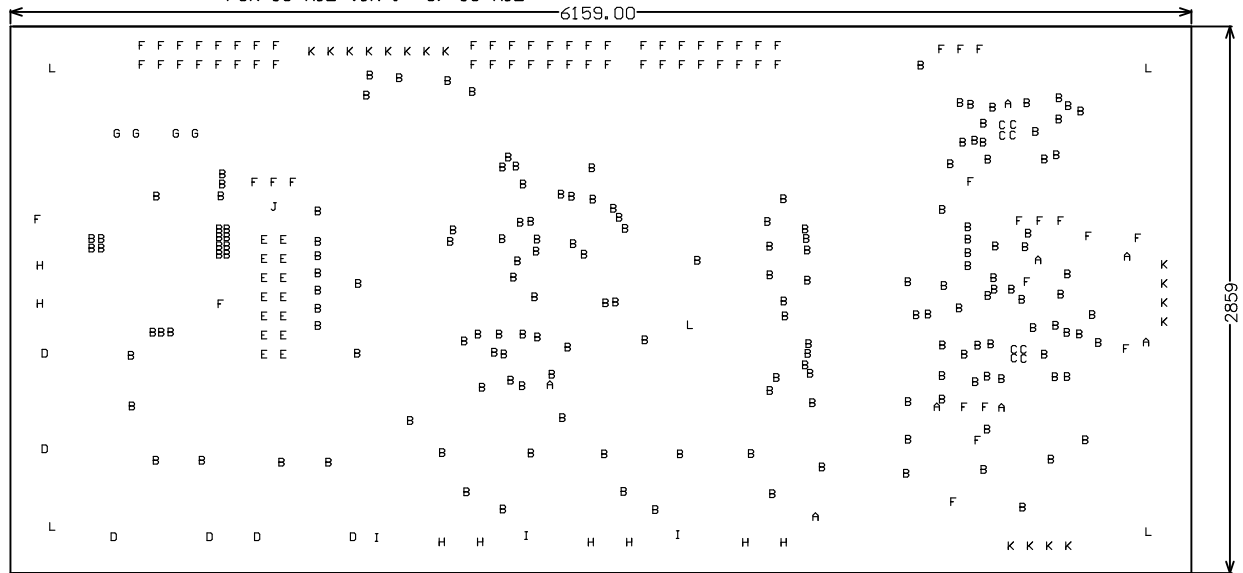
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00454	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 9/29/2015 2:48:53 PM	TEXAS INSTRUMENTS	



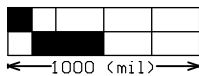
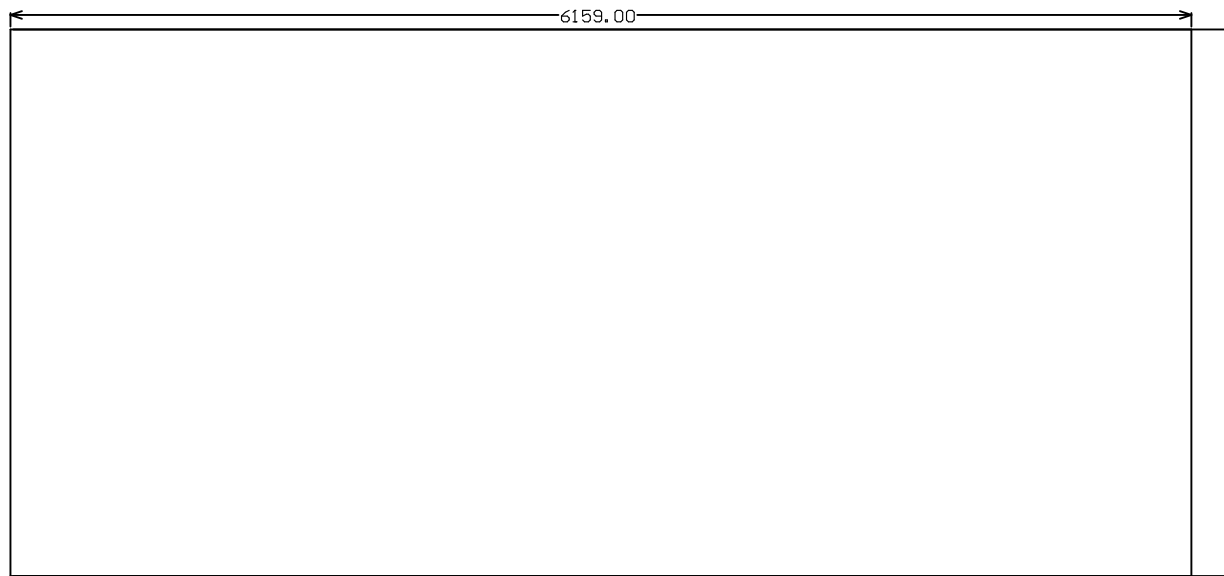
Symbol	Hit Count	Tool Size	Physical Length	Rout Path Length	Plated	Hole Type
C	8	12mil (0.305mm)			PTH	Round
B	172	16mil (0.406mm)			PTH	Round
A	8	20mil (0.508mm)			PTH	Round
D	6	33.622mil (0.854mm)			PTH	Round
J	1	35mil (0.889mm)			NPTH	Round
E	14	35mil (0.889mm)			PTH	Round
F	68	40mil (1.016mm)			PTH	Round
G	4	40.945mil (1.04mm)			PTH	Round
K	16	43.307mil (1.1mm)			PTH	Round
H	8	49.213mil (1.25mm)			PTH	Round
L	5	125.984mil (3.2mm)			PTH	Round
I	3	20mil (0.508mm)	282mil (7.163mm)	262mil (6.655mm)	NPTH	Slot
	313 Total					

Slot definitions : Rout Path Length = Calculated from tool start centre position to tool end centre position.  
Physical Length = Rout Path Length + Tool Size = Slot length as defined in the PCB layout

DRILL TOLERANCES: FOR PTH +/-3MILS  
FOR NPTH +/-2MILS  
FOR 12 MIL VIA : +0/-12 MIL  
FOR 16 MIL VIA : +0/-16 MIL



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00454	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 9/29/2015 2:48:54 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00454	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Board Dimensions	GENERATED : 9/29/2015 2:48:54 PM	TEXAS INSTRUMENTS	

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